

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1-26. (Canceled).

27. **(Currently Amended):** A transparent polymer substrate, formed by a solvent casting method, having a water absorption coefficient of 0.7% or less for transparent conductive substrate and having a total light transmittance of 80% or more, which comprises a polycarbonate resin having ~~a bisphenol component comprising~~ bisphenol A and 9,9-bis(4-hydroxy-3-methylphenyl)fluorene ~~bisphenol as bisphenol components.~~

28. **(Currently Amended):** A transparent polymer substrate according to Claim 27, wherein the ~~polycarbonate resin is a copolymer having 9,9-bis(4-hydroxy-3-methylphenyl)fluorene-bisphenol and bisphenol A as bisphenol components, wherein the~~ bisphenol A is present in an amount of 10 to 90 mol%.

29. **(Currently Amended):** A transparent polymer substrate according to Claim 27, wherein the ~~polycarbonate resin is a polycarbonate copolymer having bisphenol A and 9,9-bis(4-hydroxy-3-methylphenyl)fluorene as bisphenol components~~transparent polymer substrate has a thickness in the range of 0.02 to 0.7 mm.